

B i m g n n k o d i

The

Absolute Maximum Ratings at $T_j=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	600	V
Gate-source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^{\circ}\text{C}$	I_D	36	A
Continuous drain current ¹⁾ , $T_C=100^{\circ}\text{C}$		22.8	
Pulsed drain current ²⁾ , $T_C=25^{\circ}\text{C}$	$I_{D, pulse}$	108	A
Continuous diode forward current ¹⁾ , $T_C=25^{\circ}\text{C}$	I_S	36	A
Diode pulsed current ²⁾ , $T_C=25^{\circ}\text{C}$	$I_{S, pulse}$	108	A
Power dissipation ³⁾ , $T_C=25^{\circ}\text{C}$	P_D	261	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	845	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\dots 480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\dots 480\text{ V}$, $I_{SD} = I_D$	dv/dt	50	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^{\circ}\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		3231		pF	$V_{GS}=0\text{ V}$, $V_{DS}=50\text{ V}$, $f=100\text{ KHz}$
Output capacitance	C_{oss}		223.8		pF	
Reverse transfer capacitance	C_{rss}		2.2		pF	
Turn-on delay time	$t_{d(on)}$		40.2		ns	$V_{GS}=10\text{ V}$, $V_{DS}=400\text{ V}$, $R_G=2.5\ \Omega$, $I_D=16\text{ A}$
Rise time	t_r		29.4		ns	
Turn-off delay time	$t_{d(off)}$		87.2		ns	
Fall time	t_f		8.4		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		57.8		nC	$V_{GS}=10\text{ V}$, $V_{DS}=400\text{ V}$, $I_D=16\text{ A}$
Gate-source charge	Q_{gs}		17.2		nC	
Gate-drain charge	Q_{gd}		18.8		nC	
Gate plateau voltage	$V_{plateau}$		5.9		V	

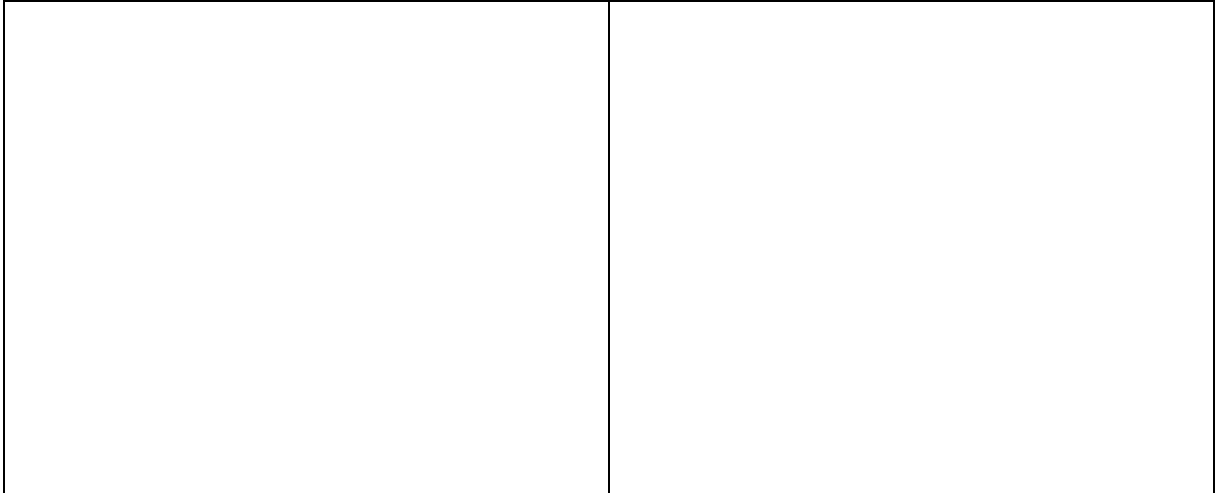
Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V_{SD}			1.4	V	$I_S=36\text{ A}$, $V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		138		ns	$I_S=16\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		756		nC	
Peak reverse recovery current	I_{rrm}		10.1		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{JA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^\circ\text{C}$.
- 5) $V_{DD}=100\text{ V}$, $V_{GS}=10\text{ V}$, $L=80\text{ mH}$, starting $T_j=25\text{ }^\circ\text{C}$.

Electrical Characteristics Diagrams



OSG60R099HEZF

Enhancement Mode N-Channel Power MOSFQ

Test circuits and waveforms

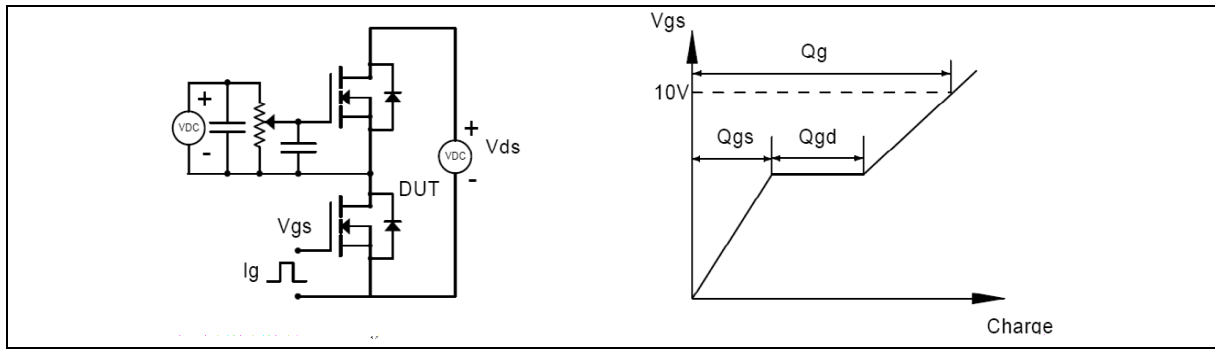


Figure 1. Gate charge test circuit & waveform

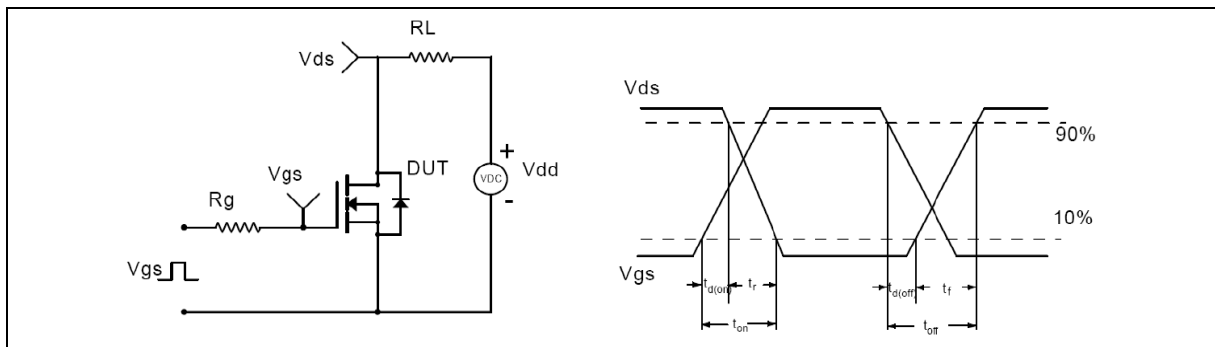


Figure 2. Switching time test circuit & waveforms

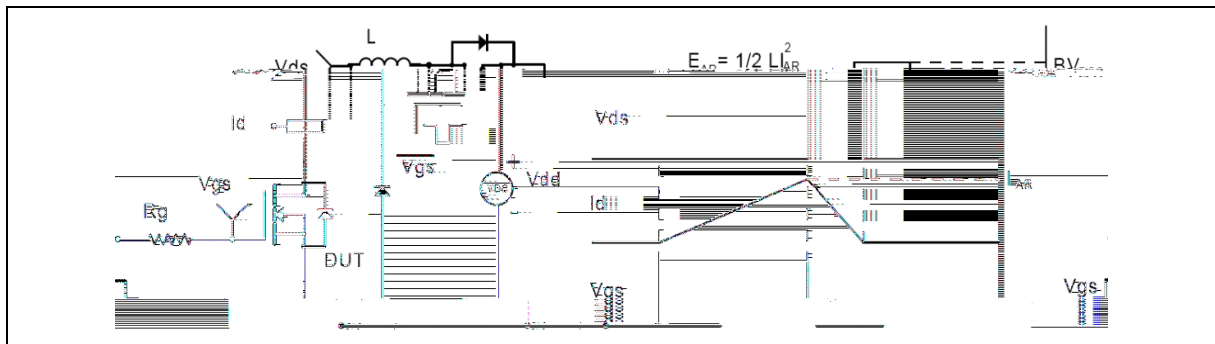


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

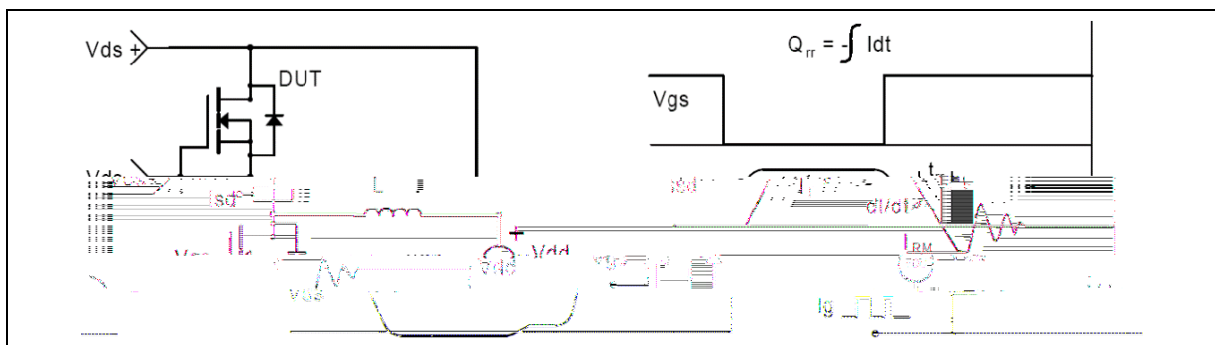


Figure 4. Diode reverse recovery test circuit & waveforms

Ordering Information

Package Type	Units/ Tube	Tubes/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO247-J	30	20	600	5	3000